

Special Issue

Wearable Electronics: Advances in Design, Materials, Fabrication, and Applications

Message from the Guest Editors

Wearable electronics have attracted significant research attention in recent years due to their transformative potential in fields such as digital medicine, human-machine interfaces, electronic skin (e-skin), and soft robotics. This Special Issue aims to showcase the latest breakthroughs, ongoing challenges, and emerging opportunities in wearable electronics. We invite contributions from leading experts, emerging investigators, and researchers working on wearable technologies, including physiological sensors and electrochemical biosensors. We welcome insightful perspectives, commentaries, reviews, and future outlooks on the subject. Submissions are encouraged to focus on innovative design strategies, novel sensing materials, advanced fabrication techniques, and their impactful applications. We will accept for publication full-length research articles and concise communications. By addressing key challenges and exploring forward-looking prospects, this Special Issue aims to inspire continued innovation and drive meaningful advancements in digital medicine, e-skin, prosthetics, and body sensor networks. We look forward to receiving your submissions!

Guest Editors

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